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N-CHANNEL ENHANCEMENT MODE MOSFET PowerDI

Product Summary

V _{(BR)DSS}	R _{DS(ON)} Max	I _D Max T _C = +25°C
	6mΩ @ V _{GS} = 10V	
30V	10mΩ @ V _{GS} = 4.5V	55.6A

Features and Benefits

- Low R_{DS(ON)} Ensures On-State Losses are Minimized
- Excellent Q_{GD} × R_{DS(ON)} Product (FOM)
- Advanced Technology for DC-DC Converts
- Small Form Factor Thermally Efficient Package Enables Higher Density End Products
- Occupies just 33% of the Board Area Occupied by SO-8 Enabling Smaller End Product
- 100% UIS (Avalanche) Rated
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

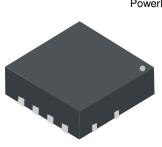
Description and Applications

This MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}), yet maintain superior switching performance, making it ideal for high efficiency power management applications.

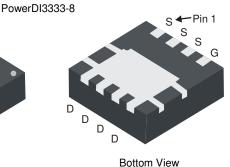
- Backlighting
- Power Management Functions
- DC-DC Converters

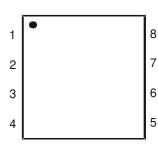
Mechanical Data

- Case: PowerDI[®]3333-8
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram
- Terminal Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 🚱
- Weight: 0.072 grams (Approximate)

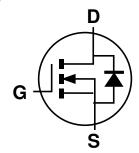












Equivalent Circuit

Ordering Information (Note 4)

Part Number	Case	Packaging
DMT3006LFG-7	PowerDI3333-8	2,000/Tape & Reel
DMT3006LFG-13	PowerDI3333-8	3,000/Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



SK1 = Product Type Marking Code YYWW = Date Code Marking YY = Last Two Digits of Year (ex: 16 = 2016) WW = Week Code (01 ~ 53)



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage	V_{DSS}	30	V	
Gate-Source Voltage	V_{GSS}	±20	V	
Continuous Drain Current (Note 6) V _{GS} = 10V	$T_C = +25$ °C $T_C = +70$ °C	ΙD	55.6 44.4	Α
Continuous Drain Current (Note 5) V _{GS} = 10V	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	ΙD	16.0 12.8	А
Maximum Continuous Body Diode Forward Current (Note 5)	I _S	2	Α	
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)	I _{DM}	80	Α	
Avalanche Current, L=0.1mH	I _{AS}	25	Α	
Avalanche Energy, L=0.1mH	E _{AS}	31	mJ	

Thermal Characteristics (@ $T_A = +25$ °C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 6)	$T_C = +25^{\circ}C$	P_{D}	27.8	W
Thermal Resistance, Junction to Case (Note 6)		$R_{ heta JC}$	4.5	°C/W
Thermal Resistance, Junction to Ambient (Note 5)		$R_{\theta JA}$	54	G/VV
Operating and Storage Temperature Range		$T_{J_i} T_{STG}$	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV _{DSS}	30	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current	I _{DSS}	_	_	1	μA	$V_{DS} = 24V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = +20V, V_{DS} = 0V$ $V_{GS} = -16V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V _{GS(TH)}	1.0	_	3.0	٧	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	
Static Drain-Source On-Resistance		_	4.8	6	mΩ	$V_{GS} = 10V, I_D = 12A$	
Static Drain-Source On-Resistance	RDS(ON)	_	6.9	10		$V_{GS} = 4.5V, I_D = 12A$	
Diode Forward Voltage	V_{SD}	_	0.7	1.0	V	$V_{GS} = 0V$, $I_S = 2A$	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	C _{ISS}	_	1,320	_		V _{DS} = 15V, V _{GS} = 0V, f = 1.0MHz	
Output Capacitance	Coss	_	490	_	pF		
Reverse Transfer Capacitance	C _{RSS}	_	77	_			
Gate Resistance	R_{G}	_	1.6	_	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$	
Total Gate Charge (V _{GS} = 4.5V)	Q _G	_	10.6	_			
Total Gate Charge (V _{GS} = 10V)	Q_{G}	_	22.6	_	0	$V_{DD} = 15V, I_D = 9A$	
Gate-Source Charge	Q _{GS}	_	3.5	_	nC		
Gate-Drain Charge	Q_{GD}	_	3.5	_			
Turn-On Delay Time	t _{D(ON)}	_	2.7	_		$V_{DD} = 15V, V_{GS} = 10V,$ $R_G = 3\Omega, I_D = 9A$	
Turn-On Rise Time	t _R	_	2.7	_			
Turn-Off Delay Time	t _{D(OFF)}	_	13.7	_	ns		
Turn-Off Fall Time	t _F	_	5.5	_			
Body Diode Reverse Recovery Time	t _{RR}	_	10.5	_	ns	1 4 5 4 3 3 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4	
Body Diode Reverse Recovery Charge	Q _{RR}	_	21.1		nC	$I_F = 1.5A$, di/dt = 100A/ μ s	

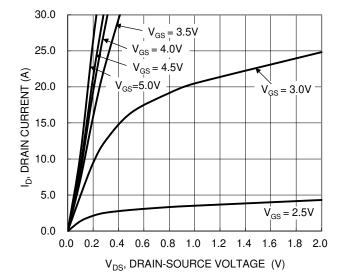
Notes: 5. $R_{\theta JA}$ is determined with the device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate. $R_{\theta JC}$ is guaranteed by design while $R_{\theta JA}$ is determined by the user's board design.

6. Thermal resistance from junction to soldering point (on the exposed drain pad).

^{7.} Short duration pulse test used to minimize self-heating effect.

^{8.} Guaranteed by design. Not subject to product testing.





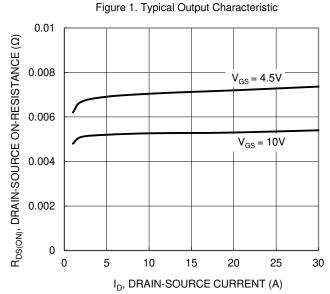


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

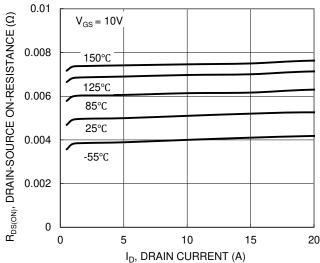


Figure 5. Typical On-Resistance vs. Drain Current and Temperature

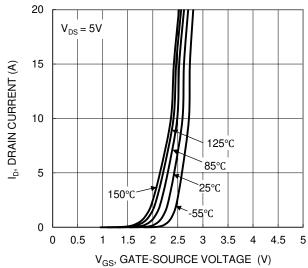


Figure 2. Typical Transfer Characteristic

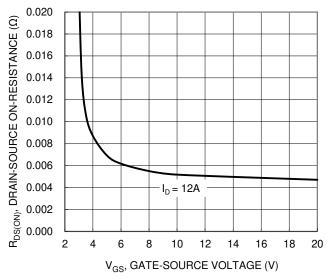


Figure 4. Typical Transfer Characteristic

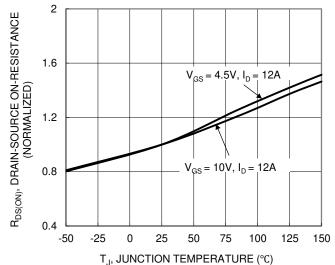


Figure 6. On-Resistance Variation with Temperature



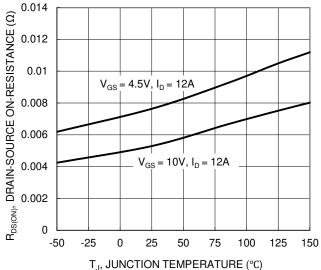
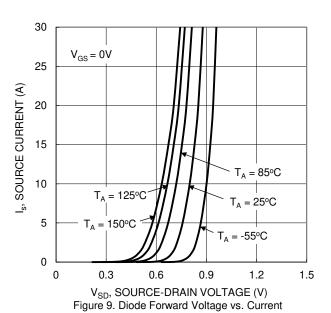


Figure 7. On-Resistance Variation with Temperature



8 6 V_{DS} = 15V, I_D = 12A 2

10

Qg - (nC) Figure 11. Gate Charge

15

20

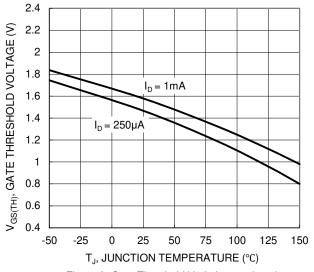
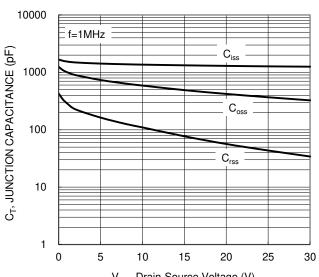


Figure 8. Gate Threshold Variation vs. Junction Temperature



V_{DS}, Drain-Source Voltage (V) Figure 10. Typical Junction Capacitance

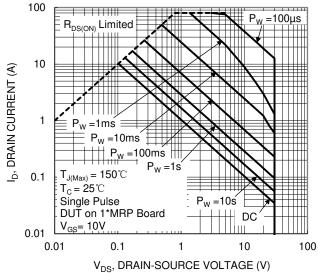


Figure 12. SOA, Safe Operation Area

0

5

10

25



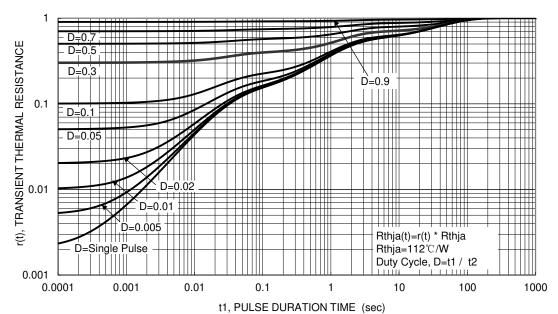


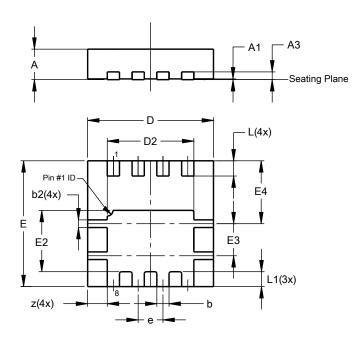
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI3333-8

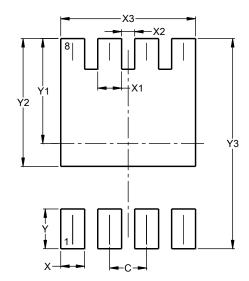


PowerDI3333-8					
Dim	Min	Max	Тур		
Α	0.75	0.85	0.80		
A1	0.00	0.05	0.02		
A3	-	-	0.203		
b	0.27	0.37	0.32		
b2	0.15	0.25	0.20		
D	3.25	3.35	3.30		
D2	2.22	2.32	2.27		
E	3.25	3.35	3.30		
E2	1.56	1.66	1.61		
E3	0.79	0.89	0.84		
E4	1.60	1.70	1.65		
е	1	-	0.65		
L	0.35	0.45	0.40		
L1	_	_	0.39		
Z	_	_	0.515		
All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI3333-8



Dimensions	Value (in mm)
С	0.650
X	0.420
X1	0.420
X2	0.230
Х3	2.370
Υ	0.700
Y1	1.850
Y2	2.250
Y3	3.700

May 2016



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